

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	jp-2001239395-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/15 14:49
S2	2	("5849606").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/15 15:35
S3	2	("5128746").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/15 14:54
S4	2167	438/108.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:03
S5	31184	228/179.1,180.21-22.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:03
S6	3239	228/179.1,180.21,180.22.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:04
S7	39	(S4 or S6) and (reinforc\$4 near10 (epoxy or resin)) and (PCB or board or substrate) same paste same (bond\$4 or solder\$3 or join\$3) same (chip or chips or component or components)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:06
S8	1168	mori-masato.in. or onishi-hiroaki.in. or hirano-masato.in. or nishida-kazuto.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:09

S9	5	S8 and (reinforc\$4 near10 (epoxy or resin)) and (PCB or board or substrate) same paste same (bond \$4 or solder\$3 or join\$3) same (chip or chips or component or components)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:10
S10	5	S8 and (reinforc\$4 near10 (epoxy or resin)) and (PCB or board or substrate) same3 paste same3 (bond \$4 or solder\$3 or join\$3) same3 (chip or chips or component or components)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:16
S11	9	S8 and (reinforc\$4 near10 (epoxy or resin)) and (PCB or board or substrate) same (bond\$4 or solder \$3 or join\$3) same (chip or chips or component or components)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:17
S12	173	(S4 or S6) and (reinforc\$4 near10 (epoxy or resin)) and (PCB or board or substrate) same (bond\$4 or solder \$3 or join\$3) same (chip or chips or component or components)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:18
S13	134	S12 not S7	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:18
S14	104	S13 and @ad<"20040224"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:18
S15	117	("4448847" "4604644" "4855001" "4980086").PN. OR ("5128746").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/15 15:31
S16	107	S15 and @ad<"20040224"	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/15 15:31
S17	9	S16 and (reinforc\$4 near10 (epoxy or resin)) and (PCB or board or substrate) and (bond\$4 or solder\$3 or join\$3) same (chip or chips or component or components)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:32
S19	5	(S4 or S6 or S8) and (reinforc\$4 near10 (epoxy or resin)) near10 (appl\$4 or deposit\$3 or suppl\$4 or form\$3 of fill\$3) near10 paste and (substrate or board or PCB)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 15:51

S20	30	("3339274" "3959874" "4172907" "4616406" "5120678" "5148266" "5155904" "5241133" "5316788" "5397917" "5433822" "5436203" "5468681" "5581122" "5663106" "5663593" "5798563" "5824569" "5889655" "6229209").PN. OR ("6365499").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/15 16:06
S21	2	ishidoya.in. and resin and substrate and paste and solder\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 16:10
S22	4	ishidoya.in. and resin and paste and solder\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/15 16:11
S23	10	("5128746" "5985043" "5985456" "5985486" "6458472").PN. OR ("6667194").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/15 16:26
S24	17	("20010003058" "20020167077" "20030080437" "20030096452" "5975408" "6458472" "6475828" "6660560" "6667194").PN. OR ("6773958").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/15 16:29
S25	2167	438/108.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/16 12:51
S26	3239	228/179.1,180.21,180.22.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/16 12:51
S27	4	(S25 or S26) and resin and print\$3 near5 paste near10 (board or substrate) same2 (retain\$4 or keep \$3 or maintain\$3 or preserv\$3) near5 (shap\$3 or form or pattern or configuration)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/16 12:51
S28	2	("6867503").PN	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/17 12:19

S29	0	wo-2002076161-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/14 11:53
S30	1	wo-02076161-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/14 11:53
S31	320	print\$3 near5 paste near5 (adhesive or resin or flux) same (board or substrate) and (bond\$3 or join\$3 or solder\$3) near5 component\$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/14 13:32
S32	210	print\$3 near5 paste near5 (adhesive or resin) same (board or substrate) and (bond\$3 or join\$3 or solder\$3) near5 component\$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/14 13:32
S33	64	print\$3 near5 paste near5 (adhesive or resin) same (board or substrate) same (bond\$3 or join\$3 or solder\$3) near5 component\$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/14 13:33
S34	8	(bond\$3 or join\$3) near5 component \$1 same (board or substrate) and both near5 (bump\$1 or ball\$1) near5 paste	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/08 17:34
S35	2	(bond\$3 or join\$3) near5 component \$1 same (board or substrate) and (benefit or advantage) near5 (bump \$1 or ball\$1) near5 paste	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/08 17:38
S36	17	(bond\$3 or join\$3) near5 component \$1 same (board or substrate) and (benefit or advantage) same (bump \$1 or ball\$1) near5 paste	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/08 17:38
S37	40	(deposit\$3 or print\$3) near5 paste near5 (adhesive or resin) same (bump\$1 or ball\$1) and (bond\$3 or join\$3 or solder\$3) near5 component \$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/08 17:57

S38	11	\$3coat\$3 near5 paste near5 (bump \$1 or ball\$1) same (adhesive or resin) and (bond\$3 or join\$3 or solder\$3) near5 component\$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/08 18:31
S39	69	(deposit\$3 or print\$3) near5 paste near5 (adhesive or resin) near5 (layer or preform) and (bond\$3 or join\$3 or solder\$3) near5 component \$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/08 18:37
S40	10	(paste near5 (mix\$3 or flow\$3 or melt\$3) near5 resin) same (interconnect\$3 or join\$3 or bond \$3) same bump\$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/09 10:26
S41	0	jp-200414964-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/09 10:49
S42	2	jp-2004014964-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/09 10:49
S43	2422	438/108.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/09 13:09
S44	3299	228/179.1,180.21,180.22.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/09 13:09
S45	146	(S43 or S44) and (resin same (preform\$1 or sheet or layer) same paste) and (bond\$3 or join\$3 or solder\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/09 13:09
S46	832	(S43 or S44) and ((bump\$1 or ball \$1) same paste) same (bond\$3 or join\$3 or solder\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/09 14:00

S47	341	(S43 or S44) and (bump\$1 near10 paste) same (bond\$3 or join\$3 or solder\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/09 14:01
S48	4680	component same mount\$3 and resin same substrate same adhesive	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/04/09 10:31
S49	46	component near5 mount\$3 and resin same adhesive near5 (power or strength) near5 (side or surface)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/04/09 12:08
S50	26	("5901050" "6097089" "6132543" "6168859" "6249051" "6376100" "6437450").PN. OR ("6798072").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/04/09 14:19
S51	31	((US-20030096452-\$ or US-20030080437-\$ or US-20020056906-\$ or US-20050070046-\$ or US-20020155637-\$ or US-20060112543-\$ or US-20050155706-\$).did. or (US-5128746-\$ or US-7331502-\$ or US-6365499-\$ or US-6229209-\$ or US-6756685-\$ or US-6887778-\$ or US-6916538-\$ or US-6773958-\$ or US-6667194-\$ or US-5985043-\$ or US-6402013-\$ or US-5373984-\$ or US-6981317-\$ or US-5926694-\$ or US-6780668-\$ or US-6798072-\$ or US-7276436-\$).did. or (JP-06061636-\$ or JP-04018787-\$ or JP-01225391-\$ or JP-2004014964-\$ or JP-03136294-\$).did. or (WO-02076161-\$ or JP-2004025288-\$).did.	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2010/04/09 15:45
S52	3	S51 and sheet same resin same paste same thermosett\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/04/09 15:45
S53	3	S51 and cool\$3 same resin same harden\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/04/09 17:05

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